

Build Up HDI (Standard)

HDI10_2+6(8b)+2_1,45_17.5_engl

10 - Layers

Core: 0.25 mm Cu 17.5/17.5 μm



WE-Article No.:

2 + 6(8B) + 2

Customer:

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements	
Customer	WE					[μm]	[μm]	
	TOP/VS		Foil	12 μm ¹⁾		12		
					1 x 1080	60		
	2			Foil	9 μm		30	
						1 x 1080	66	
	3				17.5 μm		16	
				0,250 mm			250	
	4				17.5 μm		16	
						2 x 1080	134	
	5				17.5 μm		16	
				0,250 mm			250	
	6			17.5 μm		16		
					2 x 1080	134		
	7			17.5 μm		16		
			0,250 mm			250		
	8			17.5 μm		16		
					1 x 1080	66		
	9		Foil	9 μm		30		
					1 x 1080	60		
	BOT/RS		Foil	12 μm ¹⁾		12		

1) copper thickness outer layers: appr. 55 μm

total material thickness: 1450

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	1,45	+/-	0,11	mm	Date:	Engineer:
thickness with electro plated Cu:	1,54	+/-	0,14	mm		
total thickness with soldermask	1,60	+/-	0,16	mm		
customer requirement		+/-		mm	point:	
prepared: on 27.03.2006	by S. Keller	checked: on 04.05.2006	by M.Kress	approved: on 04.05.2006	by R.Schönholz	revision 00 page: 17+